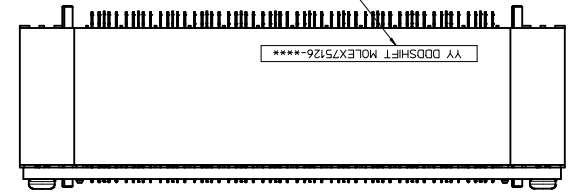


DATE CODE, MOLEX, PART NUMBER



NOTES:

1. MATERIALS FOR INTERPOSER AND HIGH SPEED DOCKING CONNECTOR:
HOUSING: LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, 94 V-0.
WAFER: LIQUID CRYSTAL POLYMER (LCP), 94 V-0, BLACK.
CONTACTS: COPPER ALLOY
HEXAGONAL THREADED INSERT: CARBON STEEL
MACHINE SCREW: CARBON STEEL
2. THIS ASSEMBLY CONFORMS TO PRODUCT SPECIFICATION PS-75018-001.
3. THIS ASSEMBLY TO BE PACKAGED PER PK-75126-001.
4. THIS ASSEMBLY CONFORMS TO CLASS C COSMETIC SPEC. PS-45499-002.
5. RECOMMENDED DRILL SIZE: 0.66±0.03 TO YIELD FINISHED PLATED THROUGH HOLE OF 0.55±0.05.
6. USE APPLICATION TOOL 62202XXXX WHEN INSERTING INTO PCB.
7. RECOMMENDED SCREW LENGTH TO MOUNT TO PCB TO BE 5mm, PLUS MOTHER BOARD THCKNESS MIN. TORQUE REQUIREMENT: 2 IN-LBS MIN. 5 IN-LBS MAX.

CONVERT TO LEAD-FREE EC NO: UCP2013-1884 2012/11/12 DRAWN BY: J BARRA CHKD: J BARRA APPR: MILLER 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉	
	▽=0	4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DRAWN BY: KSTILES CHECKED BY: DSCHMIDG APPROVED BY: MBANKIS	DATE: 7/16/2003 DATE: 7/16/2003 DATE: 7/16/2003	TITLE	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	▽=0	ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DATE: 7/16/2003	SEE TABLE	DOCUMENT NO.	SHEET NO.	
		MATERIAL NO.		SD-75126-002		1 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

CIRCUIT SIZE	ITEM NUMBER	PLATEAU HS DOCK™	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'	DIM 'G'	PLATING FINISH	CONNECTOR WAFER TYPE
108			90.50 3.563	81.50 3.209	89.00 3.504	75.62 2.977	99.40 3.913	71.00±0.08 2.795±.003	66.00±0.08 2.598±.003	FINISH 1	WELDED
144	75126-2001	75018-3023	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-2101	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 2	
144	75126-4001	75018-3123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003		
144	75126-8101	75018-8123	111.50 4.390	102.50 4.035	110.00 4.331	96.62 3.804	120.40 4.740	92.00±0.08 3.622±.003	87.00±0.08 3.425±.003	FINISH 3	

1. PLATING FINISH:

FINISH 1: (PREVIOUSLY TIN-LEAD)

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

FINISH 2:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

0.10 MICROMETERS/4 MICROINCHES MAXIMUM GOLD OVER
3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

FINISH 3:

CONTACT INTERFACE

0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT GOLD
NICKEL UNDERPLATE OVERALL

COMPLIANT INTERFACE

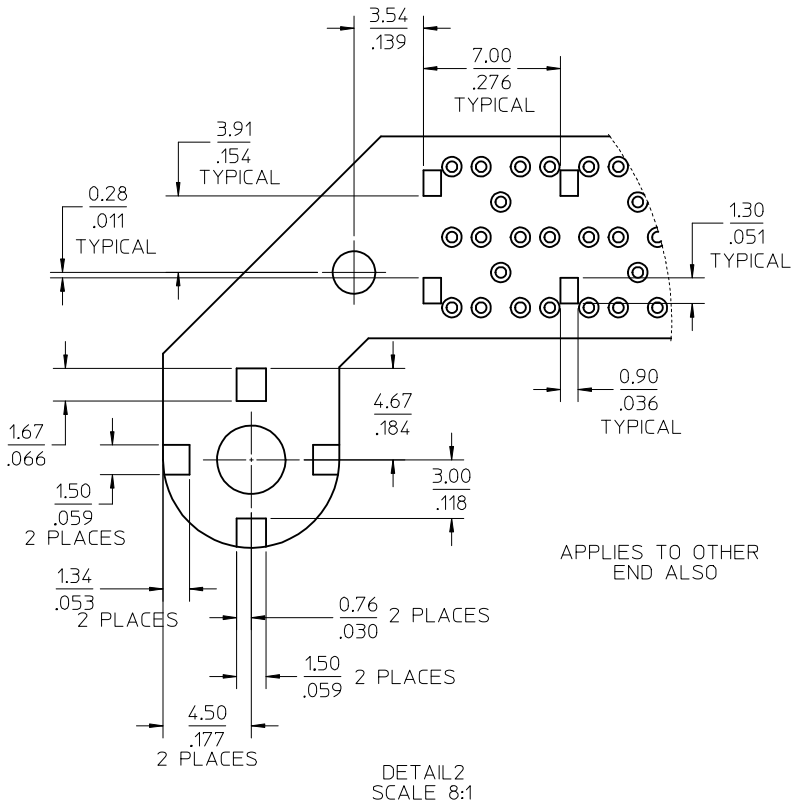
0.76 MICROMETERS/30 MICROINCHES MINIMUM SELECT MATTE-TIN OVER
NICKEL UNDERPLATE OVERALL

HOUSING

3.81 MICROMETERS/150 MICROINCHES MINIMUM NICKEL OVER
COPPER UNDERPLATE OVERALL

SEE SHEET 1 EC NO: UCP2013-1884 DRAWN BY: J. BARRA CHKD: J. BARRA APPR: MILLER 2012/11/12 2013/01/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±.010	MM/IN	2:1	METRIC	
	▽=0	3 PLACES ±.025				
	▽=0	2 PLACES ±.050				
		ANGULAR ±1/2°	DRAWN BY DATE	TITLE		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	KSTILES 7/16/2003	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING		
			CHECKED BY DATE	molex		
			DSCHMIDG 7/16/2003	SD-75126-002		
			APPROVED BY DATE	DOCUMENT NO.		
			MBANKIS 7/16/2003	2 OF 3		
			MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			SEE TABLE			

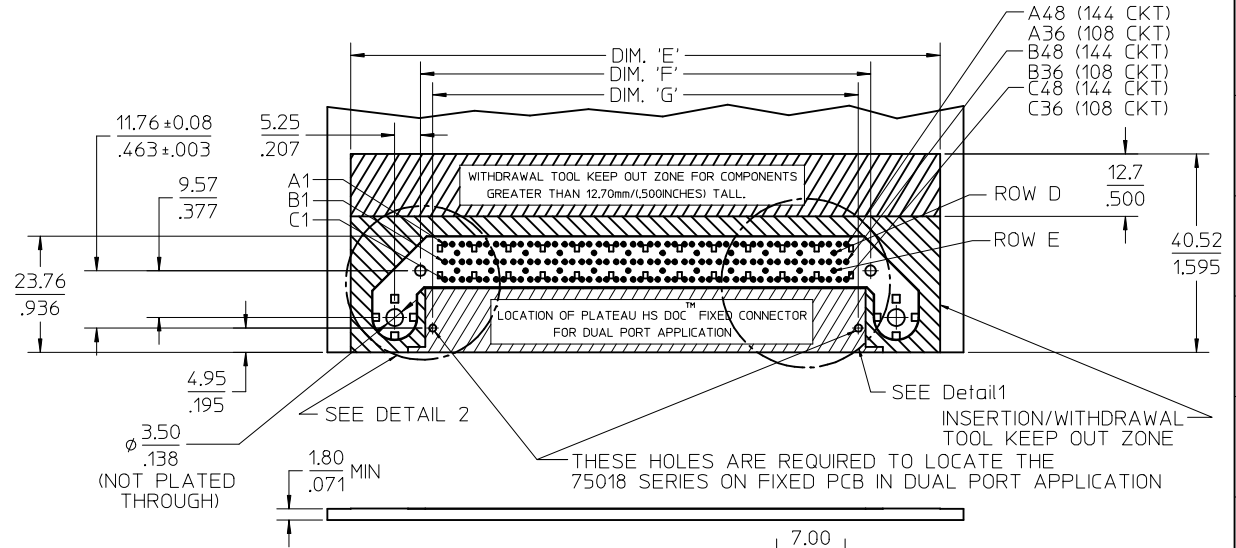
KEEP OUT AREA FOR STAND-OFFS



DETAIL2
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

APPLIES TO OTHER END ALSO



THESE HOLES ARE REQUIRED TO LOCATE THE 75018 SERIES ON FIXED PCB IN DUAL PORT APPLICATION

CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN,
A4-A3: POWER/RETURN,
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E

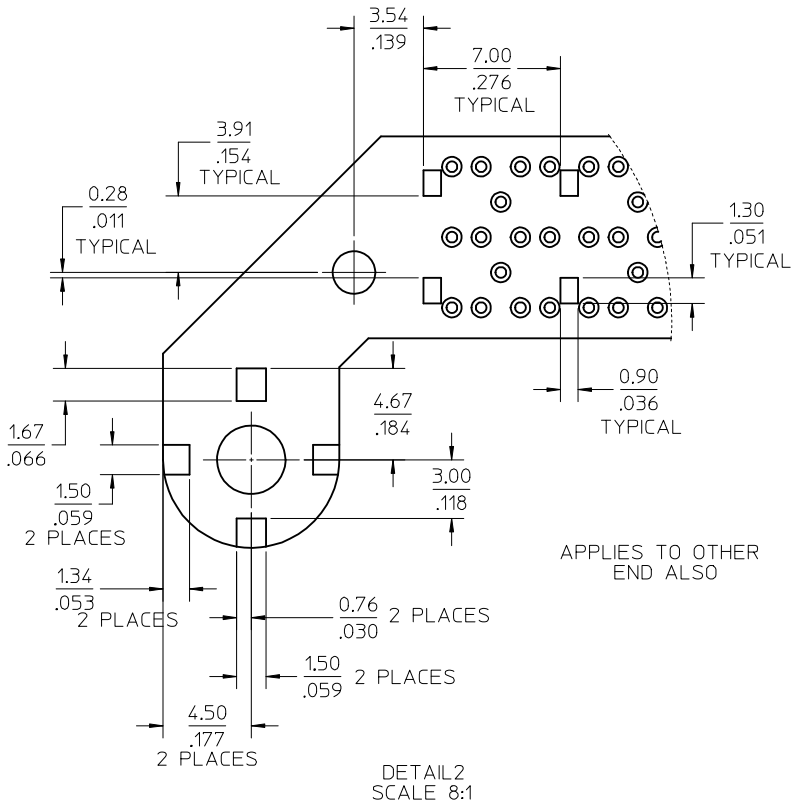
SEE SHEET 1 IEC NO: UCP2013-1884 DRAWN: TIBARRA 2012/11/12 CHKD: APPR: SMILLER 2013/01/04 DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± .010	DRAWN BY DATE			
	▽=0	3 PLACES ± .025	CHECKED BY DATE			
		1 PLACE ± .010	DSCM: DG 7/16/2003			
		0 PLACE ± .010	APPROVED BY DATE			
		ANGULAR ± 1/2°	MBANK IS 7/16/2003			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	SEE TABLE	DOCUMENT NO.	
			SIZE D		SD-75126-002	
						SHEET NO. 3 OF 3

PLATEAU HS DOCK
8.74 CL INTERPOSER
SALES DRAWING

molex

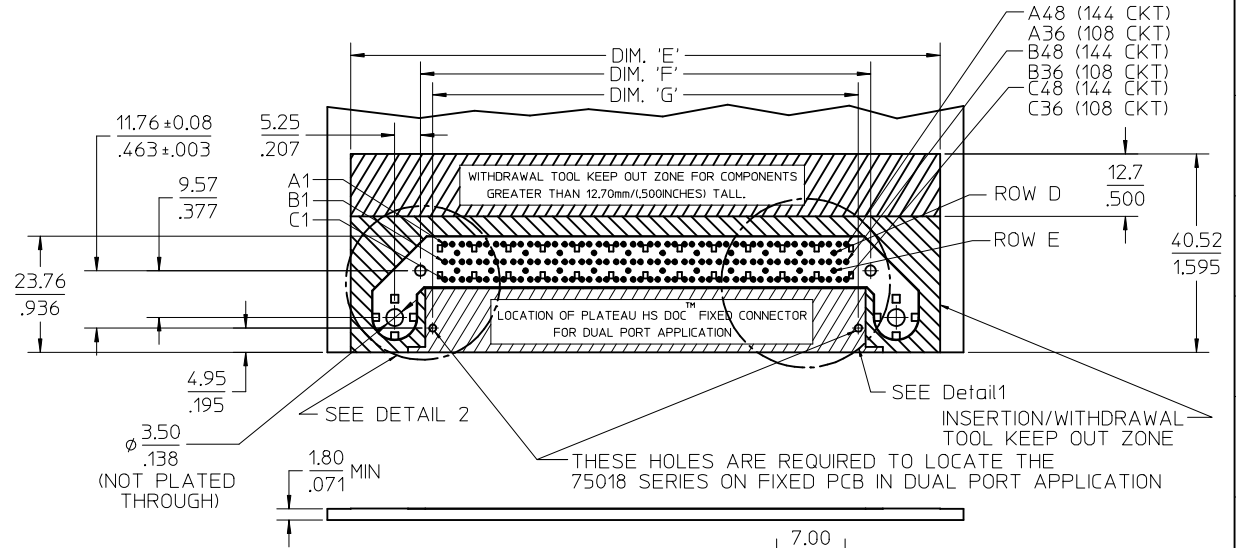
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

KEEP OUT AREA FOR STAND-OFFS



DETAIL2
SCALE 8:1

NOTE: THE DIMENSIONS DEFINING THE LOCATION AND SIZE OF THE KEEP OUT AREAS DO NOT HAVE TOLERANCES. AT A MINIMUM THE POWER PLANE MUST NOT COME INSIDE THE AREAS DEFINED BY THESE DIMENSIONS.

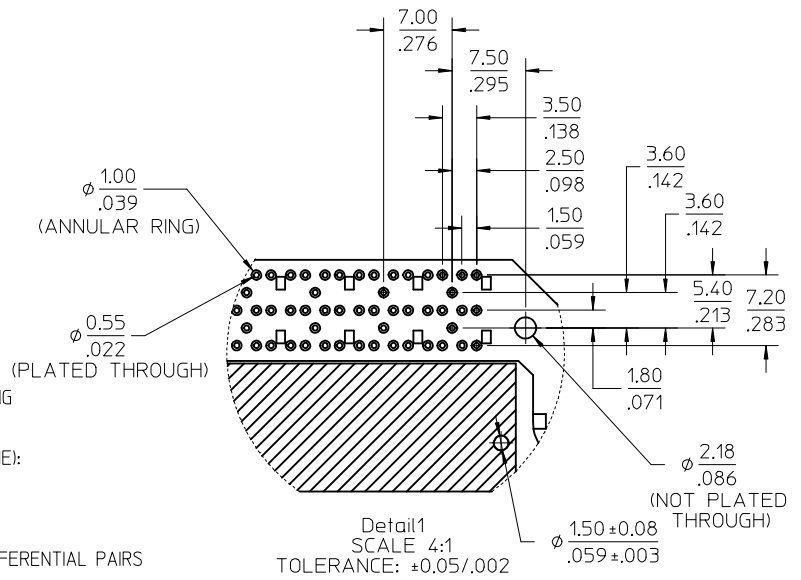


CIRCUIT DESIGNATION FOR HIGH SPEED DOCKING INTERPOSER CONNECTOR ASSEMBLY:

POWER CIRCUITS (15 AMPS PER INDICATED LINE):
A2-A1: POWER/RETURN,
A4-A3: POWER/RETURN,
C2-C1: POWER/RETURN

ALL REMAINING ROWS ARE SUITABLE FOR DIFFERENTIAL PAIRS
CURRENT CAPACITY: 300mA

GROUND CIRCUITS: ROWS D & E



Detail1
SCALE 4:1

TOLERANCE: ±0.05/.002

SEE SHEET 1 IEC NO: UCP2014-3379 DRAWN: T BARRA 2014/02/13 CHECKED: CHYD BARKER 2014/02/14 APPROVED: SMILLER 2014/03/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	2:1	METRIC	☉
	▽=0	4 PLACES ± .010	DATE	DATE	TITLE	
	▽=0	3 PLACES ± .025	T BARRA 2014/02/13	BBARKER 2014/02/14	PLATEAU HS DOCK 8.74 CL INTERPOSER SALES DRAWING	
	1 PLACE ± .010	APPROVED BY	DATE			
	0 PLACE ± .010	SMILLER 2014/03/13				
	ANGULAR ±1/2°	MATERIAL NO.	DOCUMENT NO.			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	SD-75126-2000			
		SIZE D	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

SHEET NO. 2 OF 2